

54ABT16646

16-Bit Transceivers and Registers with TRI-STATE® Outputs

General Description

The 'ABT16646 consists of bus transceiver circuits with TRI-STATE, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes to a high logic level. Control \overline{OE} and direction pins are provided to control the transceiver function. In the transceiver mode, data present at the high impedance port may be stored in either the A or the B register or in both. The select controls can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when the enable control \overline{OE} is Active LOW. In the isolation mode (control \overline{OE} HIGH), A data may be stored in the B register and/or B data may be stored in the A register.

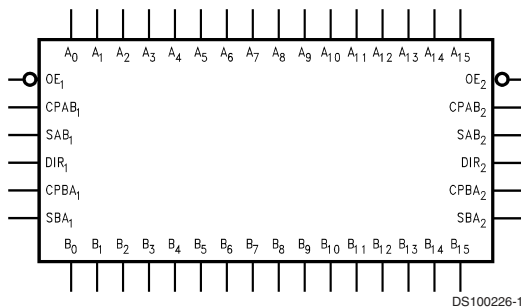
Features

- Independent registers for A and B buses
- Multiplexed real-time and stored data
- A and B output sink capability of 48 mA, source capability of 24 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability
- Standard Microcircuit Drawing (SMD) 5962-9450202

Ordering Code

Military	Package Number	Package Description
54ABT16646W-QML	WA56A	56-Lead Cerpack

Logic Symbol

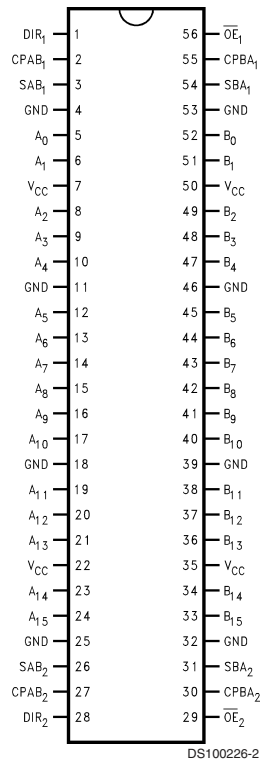


Pin Names	Description
A ₀ -A ₁₅	Data Register A Inputs/ TRI-STATE Outputs
B ₀ -B ₁₅	Data Register B Inputs/ TRI-STATE Outputs
CPAB _n , CPBA _n	Clock Pulse Inputs
SAB _n , SBA _n	Select Inputs
\overline{OE}_n	Output Enable Input
DIR	Direction Control Input

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Connection Diagram

Pin Assignment for Cerpack



**Real Time Transfer
A-Bus to B-Bus**

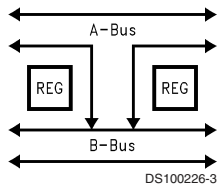


FIGURE 1.

**Storage from
Bus to Register**

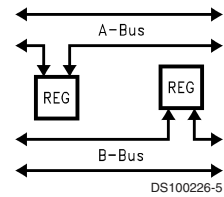


FIGURE 3.

**Real Time Transfer
B-Bus to A-Bus**

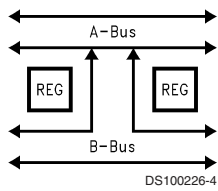


FIGURE 2.

**Transfer from
Register to Bus**

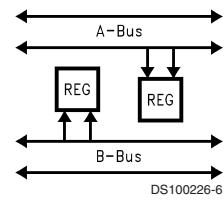


FIGURE 4.

Function Table

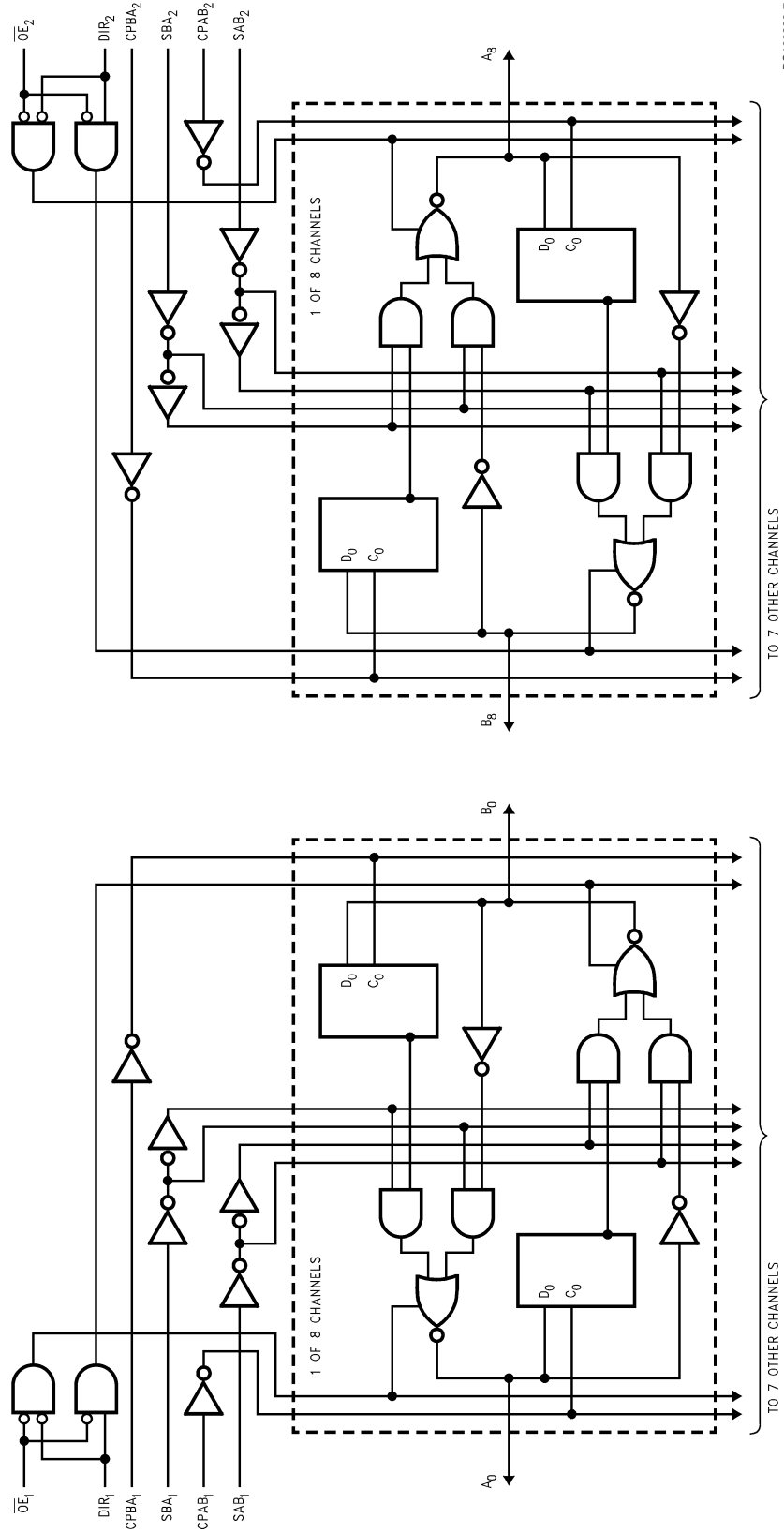
Inputs						Data I/O (Note 1)		Output Operation Mode
\overline{OE}_1	DIR ₁	CPAB ₁	CPBA ₁	SAB ₁	SBA ₁	A ₀₋₇	B ₀₋₇	
H	X	H or L	H or L	X	X	Input	Input	Isolation
H	X	N	X	X	X			Clock An Data into A Register
H	X	X	N	X	X			Clock Bn Data Into B Register
L	H	X	X	L	X	Input	Output	An to Bn—Real Time (Transparent Mode)
L	H	N	X	L	X			Clock An Data to A Register
L	H	H or L	X	H	X			A Register to Bn (Stored Mode)
L	H	N	X	H	X			Clock An Data into A Register and Output to Bn
L	L	X	X	X	L	Output	Input	Bn to An—Real Time (Transparent Mode)
L	L	X	N	X	L			Clock Bn Data into B Register
L	L	X	H or L	X	H			B Register to An (Stored Mode)
L	L	X	N	X	H			Clock Bn into B Register and Output to An

H = HIGH Voltage Level X = Immaterial

L = LOW Voltage Level N = LOW-to-HIGH Transition.

Note 1: The data output functions may be enabled or disabled by various signals at the \overline{OE} and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the appropriate clock inputs. Also applies to data I/O (A and B: 8-15) and #2 control pins.

Logic Diagram



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Absolute Maximum Ratings (Note 2)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	
Ceramic	-55°C to +175°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 3)	-0.5V to +7.0V
Input Current (Note 3)	-30 mA to +5.0 mA
Voltage Applied to Any Output in the Disable or Power-Off State	-0.5V to +5.5V
in the HIGH State	-0.5V to V _{CC}
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
DC Latchup Source Current	-500 mA

Over Voltage Latchup (I/O)

10V

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	-55°C to +125°C
Supply Voltage	
Military	+4.5V to +5.5V
Minimum Input Edge Rate	($\Delta V/\Delta t$)
Data Input	50 mV/ns
Enable Input	20 mV/ns
Clock Input	100 mV/ns

Note 2: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 3: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter	ABT16646			Units	V _{CC}	Conditions	
		Min	Typ	Max				
V _{IH}	Input HIGH Voltage	2.0			V		Recognized HIGH Signal	
V _{IL}	Input LOW Voltage			0.8	V		Recognized LOW Signal	
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA (Non I/O Pins)	
V _{OH}	Output HIGH Voltage	54ABT 54ABT	2.5 2.0				I _{OH} = -3 mA, (A _n , B _n) I _{OH} = -24 mA, (A _n , B _n)	
V _{OL}	Output LOW Voltage	54ABT		0.55	V	Min	I _{OL} = 48 mA, (A _n , B _n)	
V _{ID}	Input Leakage Test		4.75		V	0.0	I _{ID} = 1.9 μ A, (Non-I/O Pins) All Other Pins Grounded	
I _{IH}	Input HIGH Current			5	μ A	Max	V _{IN} = 2.7V (Non-I/O Pins) (Note 5) V _{IN} = V _{CC} (Non-I/O Pins)	
I _{BVI}	Input HIGH Current Breakdown Test			7	μ A	Max	V _{IN} = 7.0V (Non-I/O Pins)	
I _{BVIT}	Input HIGH Current Breakdown Test (I/O)			100	μ A	Max	V _{IN} = 5.5V (A _n , B _n)	
I _{IL}	Input LOW Current			-5	μ A	Max	V _{IN} = 0.5V (Non-I/O Pins) (Note 5) V _{IN} = 0.0V (Non-I/O Pins)	
I _{IH} + I _{OZH}	Output Leakage Current			50	μ A	0V-5.5V	V _{OUT} = 2.7V (A _n , B _n); \overline{OE} = 2.0V	
I _{IL} + I _{OZL}	Output Leakage Current			-50	μ A	0V-5.5V	V _{OUT} = 0.5V (A _n , B _n); \overline{OE} = 2.0V	
I _{OS}	Output Short-Circuit Current			-100	-275	mA	Max	V _{OUT} = 0V (A _n , B _n)
I _{CEx}	Output HIGH Leakage Current			50	μ A	Max	V _{OUT} = V _{CC} (A _n , B _n)	
I _{ZZ}	Bus Drainage Test			100	μ A	0.0V	V _{OUT} = 5.5V (A _n , B _n); All Others GND	
I _{CCH}	Power Supply Current			2.0	mA	Max	All Outputs HIGH	
I _{CCL}	Power Supply Current			60	mA	Max	All Outputs LOW	
I _{CCZ}	Power Supply Current			2.0	mA	Max	Outputs TRI-STATE; All Others GND	
I _{CCT}	Additional I _{CC} /Input			2.5	mA	Max	V _I = V _{CC} - 2.1V All Other Outputs at V _{CC} or GND	
I _{CCD}	Dynamic I _{CC} (Note 5)	No Load		0.23	mA/MHz	Max	Outputs Open \overline{OE} , DIR, and SEL = GND, Non-I/O = GND or V _{CC} (Note 4) One Bit toggling, 50% duty cycle	

DC Electrical Characteristics (Continued)

Note 4: For 8-bit toggling, $I_{CCD} < 1.4$ mA/MHz.

Note 5: Guaranteed but not tested.

Symbol	Parameter	Min	Max	Units	V_{CC}	Conditions
						$C_L = 50$ pF, $R_L = 500\Omega$ $T_A = 25^\circ\text{C}$ (Note 6)
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}		1.0	V	5.0	$T_A = 25^\circ\text{C}$ (Note 6)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}		-1.5	V	5.0	$T_A = 25^\circ\text{C}$ (Note 6)

Note 6: Max number of outputs defined as (n). n - 1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.

AC Electrical Characteristics

Symbol	Parameter	54ABT		Units
		$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 50$ pF		
		Min	Max	
f_{max}	Max Clock Frequency	125		MHz
t_{PLH}	Propagation Delay	1.0	6.9	ns
t_{PHL}	Clock to Bus	1.0	7.7	
t_{PLH}	Propagation Delay	1.0	5.8	ns
t_{PHL}	Bus to Bus	1.0	7.0	
t_{PLH}	Propagation Delay	1.0	7.1	ns
t_{PHL}	SBA _n or SAB _n to A _n to B _n	1.0	7.2	
t_{PZH}	Enable Time	1.0	6.4	ns
t_{PZL}	\overline{OE}_n to A _n or B _n	1.0	6.5	
t_{PHZ}	Disable Time	1.0	7.6	ns
t_{PLZ}	\overline{OE}_n to A _n or B _n	1.0	6.5	
t_{PZH}	Enable Time	1.0	6.4	ns
t_{PZL}	DIR _n to A _n or B _n	1.0	6.7	
t_{PHZ}	Disable Time	1.0	8.1	ns
t_{PLZ}	DIR _n to A _n or B _n	1.0	7.1	

AC Operating Requirements

Symbol	Parameter	54ABT		Units
		$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 50$ pF		
		Min	Max	
$t_S(H)$ $t_S(L)$	Setup Time, HIGH or LOW Bus to Clock	4.0		ns
$t_H(H)$ $t_H(L)$	Hold Time, HIGH or LOW Bus to Clock	0.5		ns
$t_W(H)$ $t_W(L)$	Pulse Width, HIGH or LOW	4.3		ns

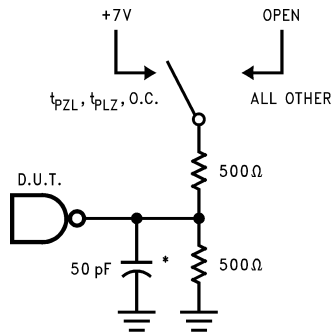
Capacitance

Symbol	Parameter	Typ	Units	Conditions
$T_A = 25^\circ\text{C}$				
C_{IN}	Input Capacitance	5	pF	$V_{CC} = 0\text{V}$ (non I/O pins)
$C_{I/O}$ (Note 7)	Output Capacitance	11	pF	$V_{CC} = 5.0\text{V}$ (A _n , B _n)

Capacitance (Continued)

Note 7: $C_{I/O}$ is measured at frequency, $f = 1$ MHz, per MIL-STD-883B, Method 3012.

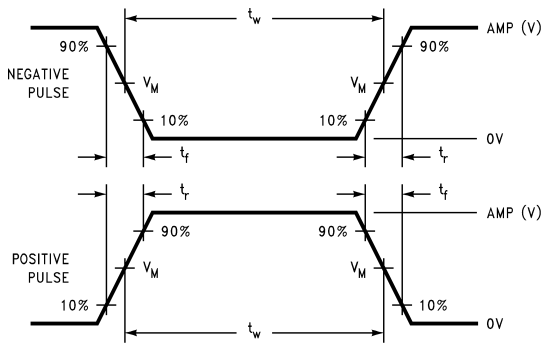
AC Loading



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*Includes jig and probe capacitance

FIGURE 5. Standard AC Test Load

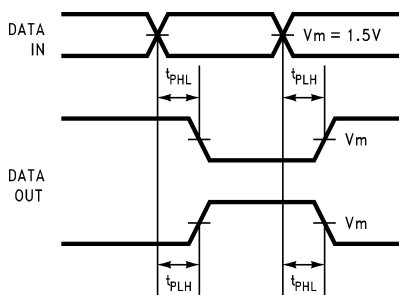


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FIGURE 6. $V_M = 1.5V$ Input Pulse Requirements

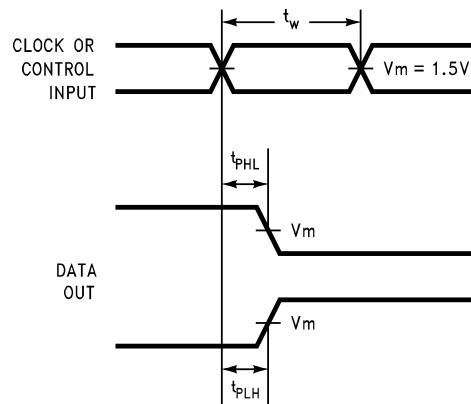
Amplitude	Rep. Rate	t_w	t_r	t_f
3V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 7. Test Input Signal Requirements



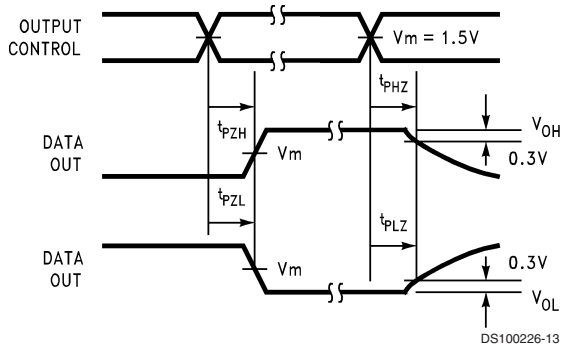
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FIGURE 8. Propagation Delay Waveforms for Inverting and Non-Inverting Functions



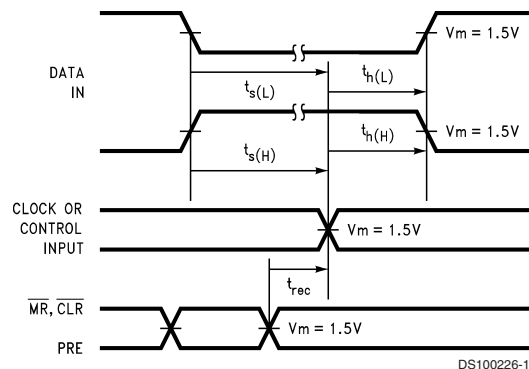
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FIGURE 9. Propagation Delay, Pulse Width Waveforms



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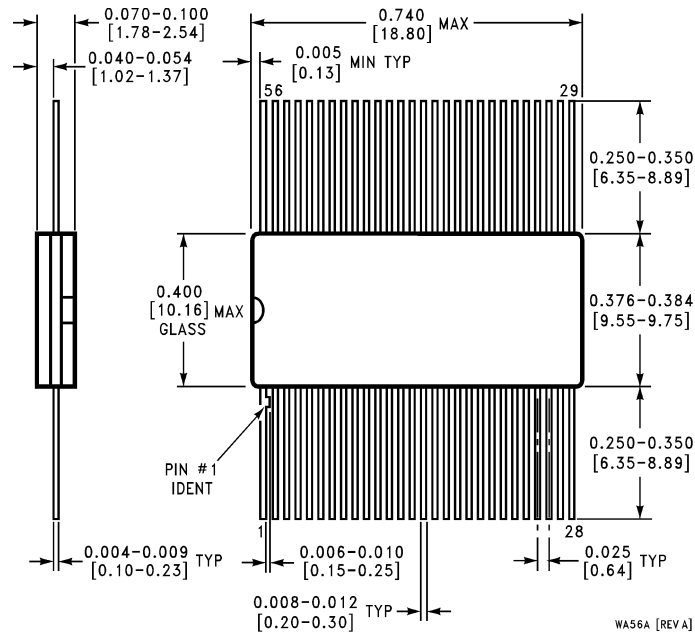
FIGURE 10. TRI-STATE Output HIGH and LOW Enable and Disable Times



DS100226-14

FIGURE 11. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted



56-Lead Cerpack
NS Package Number WA56A

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